

POWER DISSIPATION (DFN(PLP)2514-6)

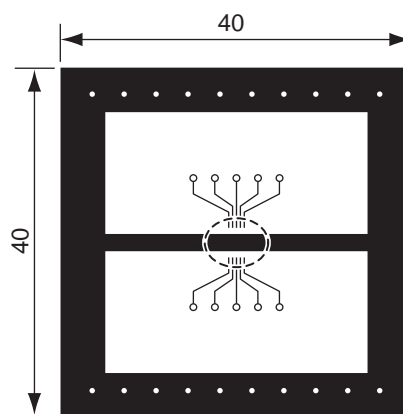
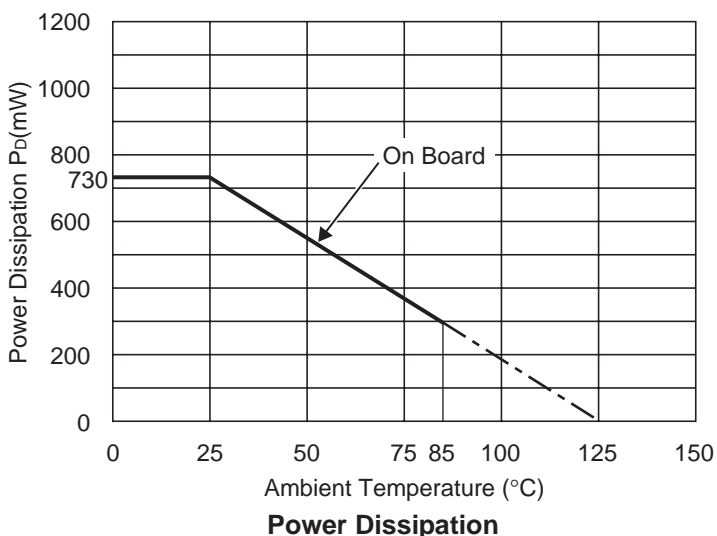
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.54mm × 30pcs

Measurement Result (T_{opt}=25°C, T_{jmax}=125°C)

	Standard Land Pattern
Power Dissipation	730mW
Thermal Resistance	$\theta_{ja}=(125-25^\circ\text{C})/0.73\text{W}=137^\circ\text{C/W}$



Measurement Board Pattern

○ IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN (DFN(PLP)2514-6)

